

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT7584839

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ROY EDWARD MEADE	06/10/2021
CHONG ZHANG	08/09/2021
HAIWEI LU	08/13/2021
CHEN LI	08/09/2021
RECEIVING PARTY DATA	
Name:	AYAR LABS, INC.
Street Address:	3351 OLCOTT STREET
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17070601
CORRESPONDENCE DATA	
Fax Number:	(408)749-6901
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	4087746914
Email:	ken.wright@penillaip.com
Correspondent Name:	KENNETH D. WRIGHT
Address Line 1:	5619 SCOTTS VALLEY DRIVE
Address Line 2:	SUITE 280
Address Line 4:	SCOTTS VALLEY, CALIFORNIA 95066
ATTORNEY DOCKET NUMBER:	AYARP028
NAME OF SUBMITTER:	KENNETH D. WRIGHT
SIGNATURE:	/Kenneth D. Wright/
DATE SIGNED:	10/11/2022
Total Attachments: 4	
source=AYARP028_USAssign_Meade_efiled#page1.tif	
source=AYARP028_USAssign_Zhang_efiled#page1.tif	

source=AYARP028_USAssign_Lu_eFiled#page1.tif

source=AYARP028_USAssign_Li_eFiled#page1.tif

ASSIGNMENT OF PATENT APPLICATION

Whereas we the undersigned inventors have invented certain new and useful improvements as set forth in the patent application entitled:

Multi-Chip Packaging of Silicon Photonics

(Attorney Docket No. AYARP028), for which we have executed an application for a United States Letters Patent which was filed in the U.S. Patent and Trademark Office on October 14, 2020, and which bears the Application No. 17/070,601,

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we the undersigned inventors hereby:

- 1) Sell, assign and transfer to Ayar Labs, Inc., a California corporation having a place of business at 3351 Olcott Street, Santa Clara, California 95054, U.S. (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts, which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants, and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the dates indicated beside our signatures.

- | | | |
|----|--------------------------------------|------------------------|
| 1) | Signature: <u>/Roy Edward Meade/</u> | Date: <u>6/10/2021</u> |
| | Typed Name: Roy Edward Meade | |
| 2) | Signature: _____ | Date: _____ |
| | Typed Name: Chong Zhang | |
| 3) | Signature: _____ | Date: _____ |
| | Typed Name: Haiwei Lu | |
| 4) | Signature: _____ | Date: _____ |
| | Typed Name: Chen Li | |

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| 1) | Signature: _____
Typed Name: Roy Edward Meade | Date: _____ |
| | / Chong Zhang / | 8/9/2021 |
| 2) | Signature: _____
Typed Name: Chong Zhang | Date: _____ |
| 3) | Signature: _____
Typed Name: Haiwei Lu | Date: _____ |
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Typed Name: Roy Edward Meade | Date: _____ |
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Typed Name: Haiwei Lu | Date: <u>8/13/2021</u> |
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Typed Name: Chen Li | Date: _____ |

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